ABSTRACT

A semiconductor device comprising: a semiconductor element (10) having a plurality of electrodes (12); an interconnect pattern (20) electrically connected to the electrodes (12); a plurality of laminated insulating layers (41, 42 and 43); and a plurality of external terminals (30) electrically connected to the interconnect pattern (20). A plurality of holes (44, 46, and 48) are respectively formed in the insulating layers (41, 42, and 43) to form an opening portion (40) communicating from the hole (48) in the highest insulating layer (43) to the hole (44) in the lowest insulating layer (41). An external terminal (30) is provided within the opening portion (40), and the second hole (46) formed in the higher positioned second insulating layer (42) is larger than the first hole (44) formed in the lower positioned first insulating layer (41).